

MAXII Series Product Brochure

Product features

- The MAXII series product is an "instant-on" non-volatile CPLD. core
- The chip density can reach up to 2210 logic units (LE) and 8Kbits of storage space. Compared with other CPLDs,
- It can provide more I/O counts, higher performance and reliable compatibility. The product also has multi-core voltage (3.3V/2.5V/1.8V), User FLASH Storage (UFM), and In-System Programmable (ISP)
- force.
- Product Features
- Low cost, low power consumption
- "Instantaneous" function realization, non-volatile structure
- Provide fast transmission delay and clock-to-output time
- Provides four global clocks, two clocks available for each logic array block (LAB)
- UFM has a capacity of up to 8 Kbits and uses non-volatile storage
- Recommended core voltage supply 3.3V/2.5V (supports 1.8V)
- I/O multi-level interface, supports 3.3V, 2.5V, 1.8V, 1.5V
- Each IO has programmable slew rate, drive strength, bus hold and pull-up resistor capabilities
- Support hot swap
- Built-in JTAG boundary scan circuit, compatible with IEEE Std.1149.1-1990 protocol
- ISP circuit is compatible with IEEE Std.1532 protocol

Functional Block Diagram

The overall architecture of the MAXII series products is shown in the figure below:

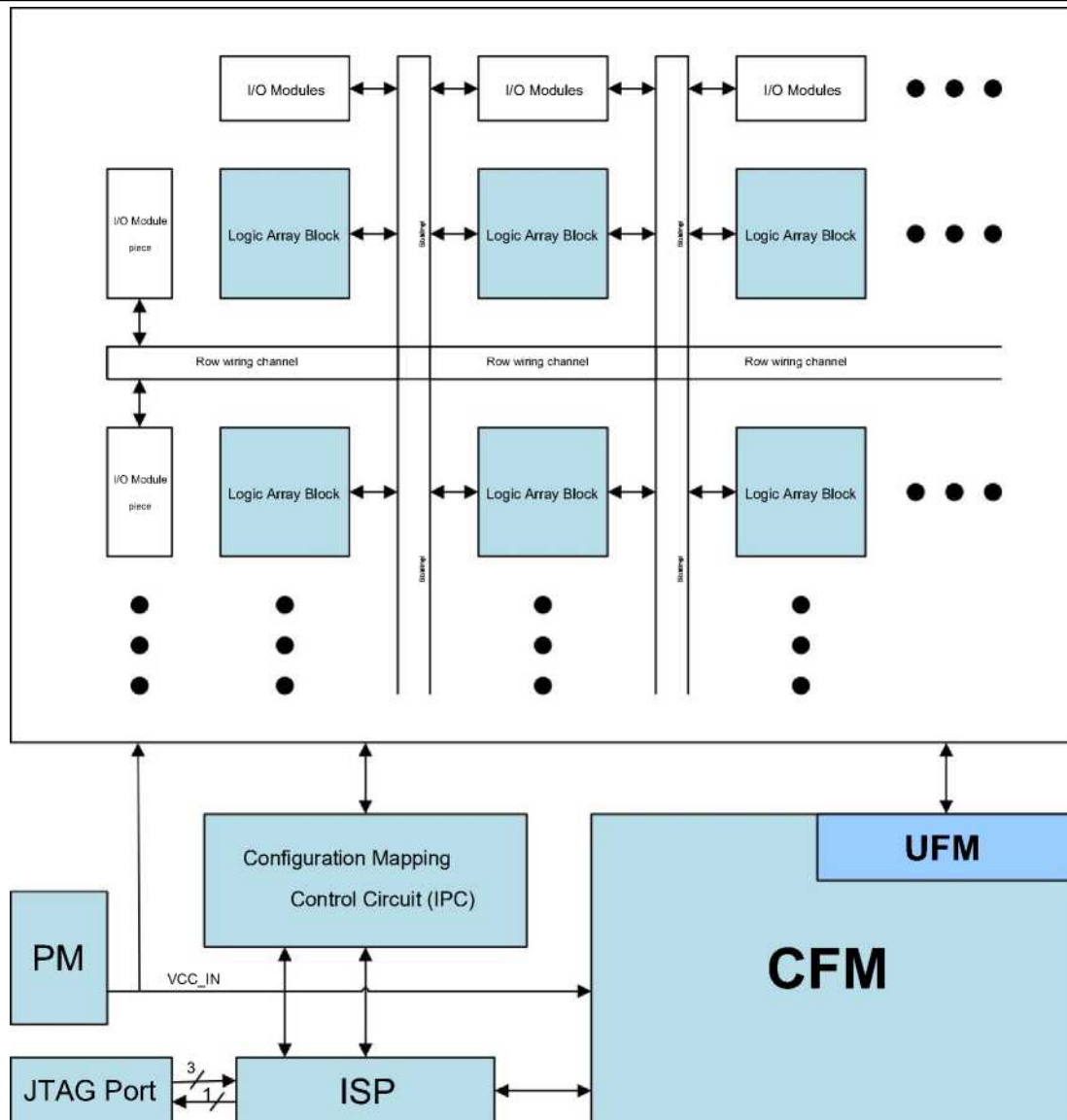


Figure 3-1 Functional module diagram

Compatible Models

Our product series	Alternative Products	Substitute Product Company	Substitute Product Country
BST240	EPM240	Altera	USA
BST570	EPM570		
BST1270	EPM1270		
BST2210	EPM2210		

Product ordering information

Product Model	Package Type	Lead Material Packag	Type Dimensions (mm)	Weight		Detailed specification number	Quality Grade	
BST240MCQFP100	CQFP100	Gold plating	Airtight packaging	16*16*3.8	ÿ2g	Q/BST 30039-2015	GJB597B-2012 Class B	
BST570MCQFP100					ÿ2.3g	Q/BST 20310-2017		
BST570MCQFP144	CQFP144			22*22*3.5	ÿ3.5g	Q/BST 30040-2015		
BST1270MCQFP144						Q/BST 20311-2017		
BST1270MCFBGA256	CFBGA256	0Pb90 solder balls	Non-hermetic packaging	17*17*4.1	ÿ3.8g	Q/BST 30041-2015		
BST2210MCFBGA256	Sn1	Sn63Pb37 solder paste				Q/BST 30042-2015		
BST2210MCFBGA324	324			19*19*4.1	ÿ4.5g	Q/BST 20281-2016		
BST240NTQFP100M3	TQFP100	Tinning	Non-hermetic packaging	16*16*1.25 i	ÿ0.6g	Q/BST 20380-2018	GJB7400 N1	
BST240						Q/BST 20195-2014	Chengdu Huawei Enterprise Standard	
BST240NQFN40 1	QFN401			5*5*0.9	ÿ0.1g	Q/BST 50160-2022	GJB7400 N1	
BST570MFBGA256	FBGA256	SAC305		17*17*1.76 i	ÿ1.15g	Q/BST 20379-2018	GJB7400 N1	
BST1270MFBGA256						Q/BST 20378-2018		
BST2210MFBGA256						Q/BST 20377-2018		
BST570EFBGA256						Q/BST 20538-2019	Chengdu Huawei	
BST1270EFBGA256						Q/BST 50019-2020	Enterprise Standard	
BST2210EFBGA256						Q/BST 20528-2019	Military Temperature Grade	
BST2210MFBGA324	FBGA324 1	Tinning		19*19*1.65	ÿ1.4g	Q/BST 50219-2022	GJB7400 N1	
BST2210FBGA256I1	FBGA256 1			17*17*1.76	ÿ1.15g	Q/BST 20393-2018	Chengdu Huawei	
BST1270ILQFP144	LQFP144 1			22*22*1.6	ÿ1.4g	Q/BST 50044-2021	Enterprise Standard Industrial Temperature Zone	